Product Change Notification

Change Notification #: 114840 - 01
Change Title: Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS

Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS,

PCN 114840-01, Product Design, Label, Product Material,

Manufacturing Process Change for QSFP Cage Attach, Regulatory Label update for Korea/Taiwan, and Firmware Upgrade

Reason for Revision: Include additional information in the Products Affected table, revise Ready to Receive Date, Firmware Upgrade, and Modify Read Me First Document

Date of Publication: October 3, 2016

Key Characteristics of the Change:
Product Design, Label, Product Material

Forecasted Key Milestones:

<table>
<thead>
<tr>
<th>Date Customer Must be Ready to Receive Post-Conversion Material:</th>
<th>Oct 7, 2016</th>
</tr>
</thead>
</table>

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.
Description of Change to the Customer:

Reason for Revision: Include additional information in the Products Affected table, revise Ready to Receive Date, Firmware Upgrade, and Modify Read Me First Document

<table>
<thead>
<tr>
<th>Affected Product Code</th>
<th>Product Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>100HFA016LS</td>
<td>Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS</td>
</tr>
<tr>
<td>100HFA016FS</td>
<td>Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS</td>
</tr>
</tbody>
</table>

Overview of Changes:

Change 1: An issue has been identified with Intel® Omni-Path adapters that can result in unseating of the mechanical cage assembly over the Quad Small Form-factor Pluggable (QSFP) connector. Unseating of the QSFP cage assembly may prevent successful insertion of a cable QSFP module into a board connector due to guide misalignment. Electrical connectivity between the cable QSFP module and board QSFP connector is not compromised by a loose QSFP cage and QSFP modules successfully inserted and latched into board QSFP connectors will maintain expected electrical and thermal performance.

Change 2: Regulatory and Compliance Certifications were successfully acquired from Korea and Taiwan. The changes include the following:
   A. The regulatory label for the product will be updated with the Korean (KC/MSIP) and Taiwan (BSMI) marks.
   B. The Read Me First document will be updated to add the Regulatory Model Numbers.
   C. The packaging label will be updated to reflect the KC labelling requirements

Change 3: The firmware shall be updated as follows, (reference release notes for 10.1 and 10.2):
   A. OptionROM UEFI firmware version 0x15 shall be replaced with version 0x29
   B. OptionROM hf1_fabric_boot_7.efi shall be replaced with UNDI firmware 0x29
   C. OptionROM configuration file hf1_platform.dat shall be replaced with hf1_platform_10_1_0_0_129
   D. TMM firmware version 10.0.0.0.696 shall be replaced with version 10.2.00.154

Change 4: Removal of the boot over fabric portion of the OptionROM make the GPL language in the Read Me First document inaccurate, as it does not apply to any of the code loaded on the card.
Product Material Change Details:

**Change 1:** Intel have added a step to the manufacturing process for all Omni-Path adapters to solder QSFP cage assembly press-fit pins to the adapter laminate to eliminate the possibility of unseating of QSFP cage assemblies. This change does not impact form, fit or function of the adapter. The manufacturing process change implemented has been evaluated to ensure no quality, reliability or functional impacts to our customers.

![Unseated QSFP cage assembly](image1)

![Properly Seated QSFP cage assembly](image2)
Change 2A: Regulatory Label showing the addition of the Korean and Taiwanese marks.
Before:

![Regulatory Label Before](image1.png)

After:

![Regulatory Label After](image2.png)

Change 2B: Regulatory change showing the addition of the Regulatory Model Numbers to the Read Me First Document. The RMF will also be revised to add a bar code under the Intel part number and to remove obsolete references to the GNU General Public License GNU.

Before:

Safety and Compliance
Regulatory Compliance Statements

Federal Communications Commission (FCC) Class A Statement

After:

Safety and Compliance
Regulatory Compliance Statements
Regulatory Model Numbers: 100HFA016, 100HFA018, 100HFA026

Federal Communications Commission (FCC) Class A Statement

Before:

| J22171-001 | 1 |

After:

| J22171-002 | 1 |
Change 2C: Package Label change to accommodate the Korean Regulatory requirements.

The following data will be added to the individual box and non-serialized carton packaging labels for Korean requirements:
1. KC Mark
2. Korean Registration Number: MSIP-REM-CPU-100HFA026
3. Equipment Name: Intel Omni-Path Host Fabric Interface Adapter
4. Regulatory Model Number: 100HFA016
5. Applicant: Intel Corporation
6. Manufacturer: Flextronics Technology

The following data will be added to the existing package label for European Union requirements:
1. CE Mark
2. Intel European Address

Individual box label, before:

![Individual box label, before](image1)

Individual box label, after:

![Individual box label, after](image2)
Non-serialized carton label, before:

![Non-serialized carton label, before](image1.jpg)

Non-serialized carton label, after:

![Non-serialized carton label, after](image2.jpg)
Change 3: The firmware shall be updated as follows:
A. OptionROM UEFI firmware version 0x15 shall be replaced with version 0x29
B. OptionROM hfi1_fabric_boot_7.efi shall be replaced with UNDI firmware 0x29
C. OptionROM configuration file hfi1_platform.dat shall be replaced with hfi1_platform_10.1.0.0.129
D. TMM firmware version 10.0.0.0.696 shall be replaced with version 10.2.00.154

Change 4: Removal of GNU General Public License reference in the Read Me First document.

Before:

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rights therein. Contractor or Manufacturer is Intel Corporation, 2200 Mission College Blvd., Santa Clara, CA 95052.

GNU General Public License GNU
This product contains firmware for Boot over Fabric functionality that is covered under the GNU General Public License, version 2, as published by the Free Software Foundation.

Legal
No license (express or implied, by estoppel or otherwise) to any intellectual property rights is granted by this document.
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After:

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by the Government constitutes acknowledgment of Intel's proprietary rights therein. Contractor or Manufacturer is Intel Corporation, 2200 Mission College Blvd., Santa Clara, CA 95052.

Legal
No license (express or implied, by estoppel or otherwise) to any intellectual property rights is granted by this document.
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Customer Impact of Change and Recommended Action:
Any adapters identified through visual inspection to have a loose or unseated QSFP cage assembly should be RMA'd to Intel for replacement or credit according to their warranty coverage. Customers with unopened adapters shipped from Intel before May 16, 2016 may also return their adapters to Intel for replacement or credit according to their warranty coverage. Adapters functioning properly in running systems require no action.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.
### Products Affected / Intel Ordering Codes:

<table>
<thead>
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<th>Product Code</th>
<th>MM#</th>
<th>Pre Change MM# Rev</th>
<th>Post Change MM# Rev</th>
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<th>Post Change AS</th>
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<td>100HFA016FS</td>
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<td>03</td>
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<td>J29320-003</td>
<td>J29321-002</td>
<td>J29321-003</td>
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### PCN Revision History:

<table>
<thead>
<tr>
<th>Date of Revision</th>
<th>Revision Number</th>
<th>Reason:</th>
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<tbody>
<tr>
<td>September 1, 2016</td>
<td>00</td>
<td>Originally Published PCN</td>
</tr>
<tr>
<td>October 3, 2016</td>
<td>01</td>
<td>Include additional information in the Products Affected table, revise Ready to Receive Date, Firmware Upgrade, and Modify Read Me First Document</td>
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</table>
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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
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